

Temperature Rise Data

Product High Anti-surge Chip Re	esistors		Seri	ies SD	R series	Туре	SDR03 EZP	Rated Power	0.3W
Test conditions Ambient temperature: Board specifications Cu foil thickness Number of layers of Cu foil Sample size Direct current application	: 25°C	1 t = 1.6 mm m	Test conditions@ Ambient tempera	ture: ons of Cu foil olication spot minal spot	: FR-4 t = 1.6 : 70µm Cu foil : 4 : 3pcs ation	·	Hot spot		
		20			•••••				
		0 0		50 電力比(%) wer rating	75	(100 0.3W)		

[Caution]

This data is the value of specific lot and specific resistance value only. It does not guarantee the variations due to different lot and product.

This data is not guaranteed. This data shall be utilized as reference data of the actual product characteristic.

When deciding the usage of the product, we cordially ask you not to only rely on this data but to have own evaluation and verification.

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